

**PATENT ASSIGNMENT**

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Wen-Cheng CHIEN (resigned)	09/02/2008
Wen-Ken HUANG (resigned)	10/09/2010
Chien-Hung LIU	04/12/2010
Joey LAI	04/12/2010
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	Xintec Inc.
<b>Street Address:</b>	9F., No. 23, Jilin Rd., Jhongli Industrial Park
<b>City:</b>	Jhongli City, Taoyuan County
<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	32062
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	12753519
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(703)205-8050
<b>Phone:</b>	703-205-8000
<b>Email:</b>	mailroom@bskb.com
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Correspondent Name:</b>	Birch, Stewart, Kolasch & Birch, LLP
<b>Address Line 1:</b>	P.O. Box 747
<b>Address Line 4:</b>	Falls Church, VIRGINIA 22040-0747
<b>ATTORNEY DOCKET NUMBER:</b>	0941-2117PUS3
<b>NAME OF SUBMITTER:</b>	Paul C. Lewis
Total Attachments: 7	

**CH \$40.00 12753519**

**501679242**

**PATENT  
 REEL: 027006 FRAME: 0267**

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## ASSIGNMENT

WHEREAS, Wen-Cheng CHIEN, Wen-Ken HUANG, Chien-Hung LIU and Joey LAI hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: IMAGE SENSOR PACKAGE WITH TRENCH INSULATOR AND FABRICATION METHOD THEREOF

Filed: April 2, 2010 Serial No. 12/753,519

Executed on: April 12, 2010

WHEREAS, Xintec Inc. of 9F., No.23, Jilin Rd., Jhongli Industrial Park, Jhongli City, Taoyuan Country 32062, Taiwan (R.O.C.) hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

\_\_\_\_\_  
Wen-Cheng CHIEN

\_\_\_\_\_  
Date:

\_\_\_\_\_  
Wen-Ken HUANG

\_\_\_\_\_  
Date:

*Chien-Hung LIU*  
\_\_\_\_\_  
Chien-Hung LIU

April 12, 2010  
\_\_\_\_\_  
Date:

*Joey Lai*  
\_\_\_\_\_  
Joey LAI

April 12, 2010  
\_\_\_\_\_  
Date:

## STATEMENT OF PROPRIETARY INTEREST

I, Chiung Yi LAI, am an employee of Xintec Inc, and hold the position of Senior Program Manager, within Xintec Inc..

Wen-Cheng CHIEN and Wen-Ken Huang were former employees of Xintec Inc., and in their former positions invented certain new and useful inventions. One such invention was described in US Application No 11/987,228, filed on Nov. 28, 2007. Xintec Inc. now develops further based on the Application No 11/987,228, and has prepared an appropriate application for filing in the United States and now obtained the filing No. 12/753,519 from the USPTO.

Wen-Cheng CHIEN and Wen-Ken Huang have been presented with a copy of the application (i.e. US Application No. 12/753,519, which is a CIP of 11/987,228) and the formal papers (e.g., combined declaration/power of attorney and assignment), but no reply was received from them. Therefore, I have executed an appropriate document on their behalf. This action of filing on their behalf is necessary in order to preserve the rights of Xintec Inc..

Attached to this statement is a copy of the inventors' statements executed by Wen-Cheng CHIEN and Wen-Ken Huang respectively, in which Wen-Cheng CHIEN and Wen-Ken Huang both agreed to assign all rights to inventions during their employment to Xintec Inc..

I hereby declare: (a) that all statements made herein of my own knowledge are true; (b) that all statements made on information and belief are believed to be true; (c) that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code; and (d) that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

  
Chiung Yi LAI

June 8, 2010

Date

## 精材科技 保密同意書

立同意書人 錢文正 茲此同意於民國 97 年 9 月 2 日自精材科技股份有限公司（以下稱「精材公司」）離職，並同意下列事項：

1. 本人同意對於任職精材公司期間內所取得、使用或知悉之精材公司所持有之任何資料及資訊（以下稱「精材專屬機密資訊」），於本人離職後，絕不洩露予任何第三人，或為自己或他人之利益使用。
2. 本同意書所稱之精材專屬機密資訊，係本人任職於精材公司期間內，直接或間接取得或知悉之所有資料及資訊，不論是書面或口頭，亦不論可否申請專利、著作權、光罩權、積體電路佈局權或其他智慧財產權，包括但不限於下列：
  - (1) 合約內容、生產方法、行銷技術與資料、通訊、採購資料、定價策略、估價程序、財務資料、組織編制、現有顧客及可能顧客之名單與需求、受僱人、顧客、供應商、經銷商之資料，以及其他與營業活動及方式有關之資料；舉凡精材之研究發展內容、擴建計劃、設備、設施、製程、產能、生產計劃、良率、產量、新產品計劃等均屬之。
  - (2) 電腦程式以及所有相關之文件。
  - (3) 發現、概念及構想，如研究發展計畫之特色及結果、程式、公式、發明以及與半導體有關之設備或知識、技術、專門技術、設計、構圖及說明書。
  - (4) 任何其他有關精材之營業活動及其他活動之事物或資料，且此種資料並非一般從事類似事業或活動之人，得以隨意知悉者。
  - (5) 由於接觸或知悉上述各項資料或資訊，因而衍生之一切構想。
3. 本人於上述任職期間，完成構思之發明或可受著作權保護之著述，本人同意屬精材公司所有，並業已告知精材公司，若精材公司擬申請專利或其他智慧財產權時，本人同意無條件配合簽署所有相關文件。
4. 本人離職前，已將本人所持有之精材公司之財產，包括全部精材專屬機密資訊，例如圖表、筆記本、報告、資料表及其他文件等，全數歸還移交精材公司，並無銷毀、交付任何第三人或佔為己有之情事。
5. 本人對與精材公司間之勞資協商過程及內容與協商結果均應保密，不得將任何資訊洩露予任何第三人，該第三人包括未參與本勞資協商之精材公司員工，並不得對外散佈及公諸不實的謠言致公司形象蒙受損失。
6. 本人如違反本同意書之任何約定，同意賠償精材公司因此所受之一切損失。

立同意書人

姓名：錢文正

身分證字號：B120576347

戶籍地址：新竹市三民路 97 號 117

中 華 民 國 97 年 9 月 2 日

PATENT

REEL: 027006 FRAME: 0272

## Confidentiality Agreement Letter

The consent letter affiant, Wen-Cheng CHIEN, hereby consents to resign from Xintec Inc. effective September 2, 2008, and further agrees to the following measures,

1. I hereby consent that of any data or information (hereinafter referred to as the Xintec's proprietary confidential information) I have obtained, utilized or come to knowledge of Xintec Inc. during my duration of employment with Xintec, and after my resignation, I shall never divulge, disclose or made known any of such information to any related third party, or allow the information be utilized to profit myself or others.
2. The term "Xintec's Proprietary Confidential Information" referred throughout the consent letter pertains to all data and information I have derived or come into contact directly or indirectly during my employment at Xintec Inc. regardless whether it be written or verbal, and regardless whether any of such data and information can be applied for registration of patent, copyright, photo mask, integrated circuit layout or other intellectual property right, including but not limited to the follows:
  - (1) The content of contracts, fabrication methods, marketing techniques and data, communications, purchasing information, pricing strategies, price estimation process, financial data, organization mechanism, name list and demands of the existing customs and potential customers, hired help, customer's suppliers, distributor information, and other business activity and method-related information, encompassing those relating to the content of research and development, expansion plans, equipment, facility, process flows, production capacity, production plans, acceptance ratios, mass production, new product planner and the like.
  - (2) Computer programming and all related documents.
  - (3) The discovery, concept and conceptualization, such as a research and development plans' characteristics and findings, programming, equations, invention and semiconductor-related equipment or knowledge, technology, proprietary technology, design, conceptual drawings or description.
  - (4) Any other Xintec-related business activity or other related activity's subject matters and information, where such information is not privy to anyone engaging in a similar enterprise or activity.
  - (5) All forms of conceptions derived from coming into contact or be given the foresaid various forms of data and information.
3. Of inventions or patentable publications that I have conceived during my foresaid employment period, I hereby consent that the information belongs to Xintec Inc, and that I have duly informed Xintec Inc, and when Xintec Inc decides to file for patent or other intellectual property registration, I hereby consent to unconditionally render my support in signing all pertinent documents.
4. Before resigning, I have returned Xintec Inc's properties held in my possession, including all of the confidential information belonging to Xintec Inc, i.e. graphics and charts, notes, reports, data sheets and other documents, and have not destroyed any of the information, or present any of which to any unrelated third party, or possess the information as my own.
5. I shall uphold strict confidentiality on the content of my labor-management negotiation process ad the result of the negotiation with Xintec Inc, and may not divulge, reveal or disclose any of which to any unrelated third party, where said third party encompasses Xintec Inc employees who may participate in future labor-management negotiations, and also may not spread or disclose any untrue rumors to result in damaging the company's image.
6. I, in the event of breaching any agreement stipulated by the consent letter, hereby consent to compensate Xintec Inc for all losses it suffers.

Affiant	:
Name	: Wen-Cheng CHIEN
I.D. Card No.	: B120576347
Household Address	: No.97-11, Sanmin Rd., East Dist., Hsinchu City 300, Taiwan (R.O.C.)

Dated: September 2, 2008

# 精材科技 保密同意書

立同意書人 黃昕振 茲此同意於民國 98 年 10 月 9 日自精材科技股份有限公司（以下稱「精材公司」）離職，並同意下列事項：

1. 本人同意對於任職精材公司期間內所取得、使用或知悉之精材公司所持有之任何資料及資訊（以下稱「精材專屬機密資訊」），於本人離職後，絕不洩露予任何第三人，或為自己或他人之利益使用。
2. 本同意書所稱之精材專屬機密資訊，係本人任職於精材公司期間內，直接或間接取得或知悉之所有資料及資訊，不論是書面或口頭，亦不論可否申請專利、著作權、光罩權、積體電路佈局權或其他智慧財產權，包括但不限於下列：
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  - (2) 電腦程式以及所有相關之文件。
  - (3) 發現、概念及構想，如研究發展計畫之特色及結果、程式、公式、發明以及與半導體有關之設備或知識、技術、專門技術、設計、構圖及說明書。
  - (4) 任何其他有關精材之營業活動及其他活動之事物或資料，且此種資料並非一般從事類似事業或活動之人，得以隨意知悉者。
  - (5) 由於接觸或知悉上述各項資料或資訊，因而衍生之一切構想。
3. 本人於上述任職期間，完成構思之發明或可受著作權保護之著述，本人同意屬精材公司所有，並業已告知精材公司，若精材公司擬申請專利或其他智慧財產權時，本人同意無條件配合簽署所有相關文件。
4. 本人離職前，已將本人所持有之精材公司之財產，包括全部精材專屬機密資訊，例如圖表、筆記本、報告、資料表及其他文件等，全數歸還移交精材公司，並無銷毀、交付任何第三人或佔為己有之情事。
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6. 本人如違反本同意書之任何約定，同意賠償精材公司因此所受之一切損失。

立同意書人

姓名：黃昕振

身分證字號：U120219320

戶籍地址：竹市經國路一段532號8樓之2

中 華 民 國 98 年 10 月 9 日



## Confidentiality Agreement Letter

The consent letter affiant, Wen-Ken HUANG, hereby consents to resign from Xintec Inc. effective October 9, 2009, and further agrees to the following measures,

1. I hereby consent that of any data or information (hereinafter referred to as the Xintec's proprietary confidential information) I have obtained, utilized or come to knowledge of Xintec Inc. during my duration of employment with Xintec, and after my resignation, I shall never divulge, disclose or made known any of such information to any related third party, or allow the information be utilized to profit myself or others.
2. The term "Xintec's Proprietary Confidential Information" referred throughout the consent letter pertains to all data and information I have derived or come into contact directly or indirectly during my employment at Xintec Inc. regardless whether it be written or verbal, and regardless whether any of such data and information can be applied for registration of patent, copyright, photo mask, integrated circuit layout or other intellectual property right, including but not limited to the follows:
  - (1) The content of contracts, fabrication methods, marketing techniques and data, communications, purchasing information, pricing strategies, price estimation process, financial data, organization mechanism, name list and demands of the existing customs and potential customers, hired help, customer's suppliers, distributor information, and other business activity and method-related information, encompassing those relating to the content of research and development, expansion plans, equipment, facility, process flows, production capacity, production plans, acceptance ratios, mass production, new product planner and the like.
  - (2) Computer programming and all related documents.
  - (3) The discovery, concept and conceptualization, such as a research and development plans' characteristics and findings, programming, equations, invention and semiconductor-related equipment or knowledge, technology, proprietary technology, design, conceptual drawings or description.
  - (4) Any other Xintec-related business activity or other related activity's subject matters and information, where such information is not privy to anyone engaging in a similar enterprise or activity.
  - (5) All forms of conceptions derived from coming into contact or be given the foresaid various forms of data and information.
3. Of inventions or patentable publications that I have conceived during my foresaid employment period, I hereby consent that the information belongs to Xintec Inc, and that I have duly informed Xintec Inc, and when Xintec Inc decides to file for patent or other intellectual property registration, I hereby consent to unconditionally render my support in signing all pertinent documents.
4. Before resigning, I have returned Xintec Inc's properties held in my possession, including all of the confidential information belonging to Xintec Inc, i.e. graphics and charts, notes, reports, data sheets and other documents, and have not destroyed any of the information, or present any of which to any unrelated third party, or possess the information as my own.
5. I shall uphold strict confidentiality on the content of my labor-management negotiation process ad the result of the negotiation with Xintec Inc, and may not divulge, reveal or disclose any of which to any unrelated third party, where said third party encompasses Xintec Inc employees who may participate in future labor-management negotiations, and also may not spread or disclose any untrue rumors to result in damaging the company's image.
6. I, in the event of breaching any agreement stipulated by the consent letter, hereby consent to compensate Xintec Inc for all losses it suffers.

Affiant :  
 Name : Wen-Ken HUANG  
 I.D. Card No. : U120214320  
 Household Address : 8F.-2, No.532, Sec. 1, Jingguo Rd., North Dist.,  
 Hsinchu City 300, Taiwan (R.O.C.)

Dated: October 9, 2010